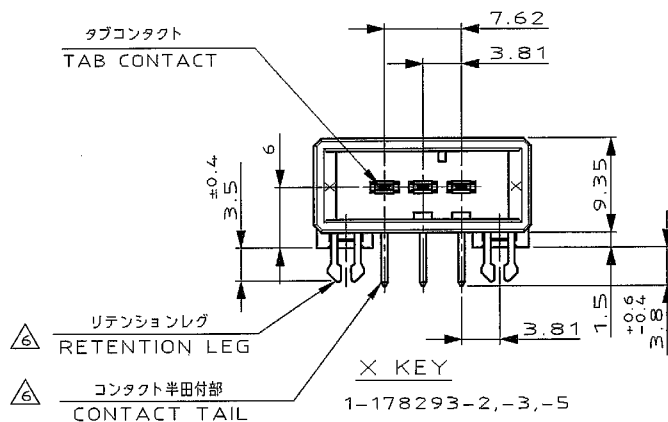
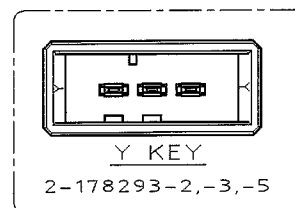
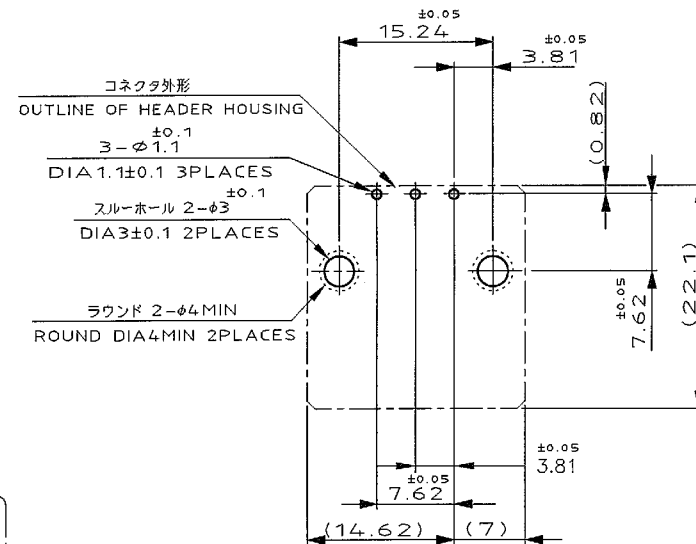
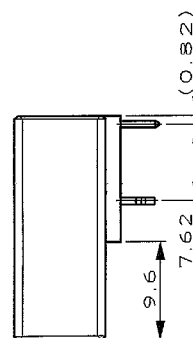
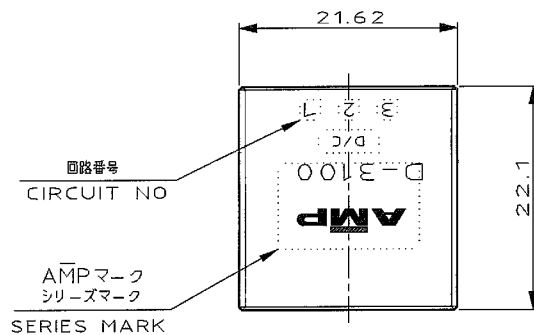




推奨基板取付け穴寸法

PC 基板厚: 1.6 ± 0.1
(非累積公差)
(コネクタ搭載面)

RECOMEND PC BOARD HOLE PATTERN

PC BOARD THICKNESS: 1.6 ± 0.1
(NOT ACCUMULATE TOLERANCE)
(CONNECTOR MOUNT SIDE)

NOTES

1. MATERIAL:HOUSING:GLASS FILED THERMO
PLASTIC,POLYESTER
CONTACT:COPPER ALLOY
RETENTION LEG:COPPER ALLOY
- A. FINISH(CONTACT AREA):0.38μMMIN GOLD PLATING
OVER Ni PLATING
- A. FINISH(CONTACT AREA):0.76μMMIN GOLD PLATING
OVER Ni PLATING
- A. FINISH(CONTACT AREA):2.0 μMMIN TIN
PLATED OVER NICKEL
- ~~A. FINISH(RETENTION LEG): TIN-LEAD PLATED
(CONTACT TAIL) OVER NICKEL~~
- A. FINISH(RETENTION LEG): TIN PLATED
(CONTACT TAIL) OVER NICKEL

注記

1. 材料：ハウジング：ガラス入り熱可塑性
ポリエステル樹脂
コンタクト：銅合金
リテンションレグ：銅合金
- ②. めっき：コンタクト：全面Ni下地
接触部：0.38 μm MIN全めっき
- ③. めっき：コンタクト：全面Ni下地
接触部：0.76 μm MIN全めっき
- ④. めっき：コンタクト：全面Ni下地
接触部：2.0 μm MINスズめっき
- ~~⑤. めっき：リテンションレグとコンタクト半田付部~~
- ニッケル下地のの上に半田めっき ——
- ⑥. めっき：リテンションレグとコンタクト半田付部：ニッケル下地のの上にスズめっき

6	4	1,2-178293-5
6	3	1,2-178293-3
6	2	1,2-178293-2
(FINISH)		製品番号 (PART NO.)

[illegible]

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WIRE RANGE		INSULATION DIA	
mm(AWG -)		mm	
MATERIAL		FINISH	
SEE NOTE 注記参照		SEE NOTE 注記参照	
DR. 20/MAR/95 K.I.KEDA		DE. 20/MAR/95 K.I.KEDA	
CHK. 23/MAR/92 S. NAITARE		APP. 23/MAR/92 S. NAITARE	
3 POS SINGLE ROW HORIZONTAL HDR ASS'Y FOR DYNAMIC 3100		一般公差 (GENERAL TOLERANCE) 100 $\pm$ 10 $\pm$ 3 100 $\pm$ 30 $\pm$ 10 $\pm$ 5 300 $\pm$ 100 $\pm$ 10 $\pm$ 3 $\pm$	
SIZE		LOC	
A3		J	
NUMBER		C- 178293	
SCALE		REV.	
2-1		C	
SHEET		1 OF 1	

(CUSTOMER DRAWING) 顧客用図面